

IN THE CLAIMS

Claims 1-10 (Canceled)

11. (Previously amended) A composition for a polishing pad which comprises a water-insoluble matrix material containing a crosslinked polymer and a water-soluble particle dispersed in the water-insoluble matrix material, wherein said water-soluble particle is provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part.

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12. (Currently amended) The composition for a polishing pad according to claim 11, wherein said water-soluble particle is an organic water-soluble particle comprising [of] at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, and/or an inorganic water-soluble particle comprising [of] at least one material selected from the group consisting of potassium acetate, potassium nitrate, potassium carbonate, potassium bicarbonate, potassium chloride, potassium bromide, potassium phosphate and magnesium nitrate.

13. (Original) The composition for a polishing pad according to claim 12, wherein the amount of said water-soluble particles is 10 to 90% by volume based on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

14. (Original) A polishing pad characterized in that at least a part of said polishing pad comprises the composition of a water-insoluble matrix material containing a crosslinked polymer and a water-soluble particle dispersed in the water-insoluble matrix material.

15. (Original) A polishing pad according to claim 14, wherein the elongation remaining after breaking is 100% or less when a test piece comprising the water-insoluble

matrix material is broken at 80°C.

16. (Original) A polishing pad according to claim 15, wherein the Shore D hardness is 35 or more.

17. (Currently amended) A composition for a polishing pad which comprises a water-insoluble matrix material containing a crosslinked polymer and an organic water-soluble particle comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, dispersed in the water-insoluble matrix material.

18. (Previously added) The composition for a polishing pad according to claim 17, wherein the elongation remaining after breaking is 100% or less when a test piece comprising the water-insoluble matrix material is broken at 80°C.

19. (Currently amended) The composition for a polishing pad according to claim 17, wherein said water-insoluble matrix material is modified with at least one group selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group and an amino group.

20. (New) The composition for a polishing pad according to claim 17, wherein said crosslinked polymer is (1) a crosslinked polymer of rubber selected from the group consisting of 1,2-polybutadiene, butadiene rubber, isoprene rubber, acrylic rubber, acrylonitrile-butadiene rubber, styrene-butadiene rubber, ethylene-propylene rubber, silicone rubber, fluorine rubber and styrene-isoprene rubber, (2) a crosslinked polymer of resin selected from the group consisting of polyethylene and polyvinylidene fluoride, or (3) an ionomer.

21. (New) The composition for a polishing pad according to claim 17, wherein the

amount of said water-soluble particles is 10 to 90% by volume based on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

22. (New) The composition for a polishing pad according to claim 17, wherein said water-soluble particle is provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part.

23. (New) The composition for a polishing pad according to claim 22, wherein said outer shell is comprised of at least one material selected from the group consisting of polypeptide, epoxy resin, polyimide, polyamide and polysilicate.

24. (New) A composition for a polishing pad which comprises a water-insoluble matrix material containing a polymer crosslinked by an organic peroxide and an organic water-soluble particle comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer dispersed in the water-insoluble matrix material.

25. (New) The composition for a polishing pad according to claim 24, wherein said crosslinked polymer is (1) a crosslinked polymer of rubber selected from the group consisting of 1,2-polybutadiene, butadiene rubber, isoprene rubber, acrylic rubber, acrylonitrile-butadiene rubber, styrene-butadiene rubber, ethylene-propylene rubber, silicone rubber, fluorine rubber and styrene-isoprene rubber, (2) a crosslinked polymer of resin selected from the group consisting of polyethylene and polyvinylidene fluoride, or (3) an ionomer.

26. (New) The composition for a polishing pad according to claim 24, wherein said water-insoluble matrix material is modified with at least one group selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group

and an amino group.

27. (New) The composition for a polishing pad according to claim 24, wherein the amount of said water-soluble particles is 10 to 90% by volume based on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

28. (New) The composition for a polishing pad according to claim 24, wherein said water-soluble particle is provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part.

29. (New) Composition for a polishing pad according to claim 28, wherein said outer shell is comprised of at least one material selected from the group consisting of polypeptide, epoxy resin, polyimide, polyamide and polysilicate.

30. (New) The composition for a polishing pad according to claim 11, wherein said crosslinked polymer is (1) a crosslinked polymer of rubber selected from the group consisting of 1,2-polybutadiene, butadiene rubber, isoprene rubber, acrylic rubber, acrylonitrile-butadiene rubber, styrene-butadiene rubber, ethylene-propylene rubber, silicone rubber, fluorine rubber and styrene-isoprene rubber, (2) a crosslinked polymer of resin selected from the group consisting of polyethylene and polyvinylidene fluoride, or (3) an ionomer.

31. (New) The composition for a polishing pad according to claim 11, wherein said water-insoluble matrix material is modified with at least one group selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group and an amino group.

32. (New) The composition for a polishing pad according to claim 11, wherein said outer shell is comprised of at least one material selected from the group consisting of polypeptide, epoxy resin, polyimide, polyamide and polysilicate.

DISCUSSION OF THE AMENDMENT

Claims ~~1-10~~^{1, 3-10} have been canceled. Claims 12, 17 and 19 have been amended by inserting an appropriate word before the recital of the Markush group therein.

New Claims 20-32 have been added. Claim 20 is supported in the specification at the paragraph bridging pages 9 and 10. Claim 21 is supported by original Claim 5. Claim 22 supported by original Claim 11. Claim 23 is supported in the specification at page 13, lines 7-10 and page 25, line 5. Claim 24 is supported by original Claim 4 and page 21, lines 21-22 and Example 1. Claims 25-29 are analogous to Claims 20, 19, and 21-23, respectively. Claims 30-32 are analogous to Claims 20, 19 and 23, respectively.

No new matter has been added by the above amendment. Claims 11-13 and 17-32 are now active; Claims 14-16 stand withdrawn from consideration.